TG-A09AB / TG-S09AB

Silicone Potting Compound

REACH Compliant | RoHS Compliant

Features

- Good thermal conductivity
- Protect electronic components after cured
- A:B=1:1
- Cured by room temperature or heating

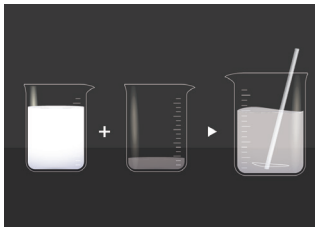
Application:

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

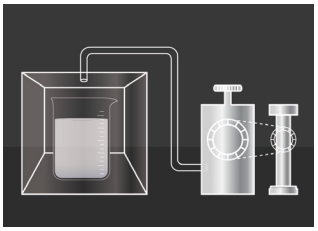
Storage:

Silicone Potting Compound has a shelf-life of 12 months from the date of manufacture, as indicated by the lot number, when stored in the original, should be unopened container at or below 25°C.

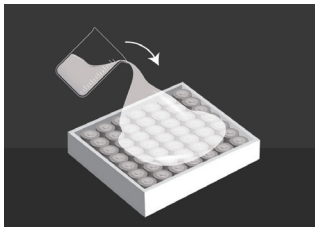
Operation Manual



① Mix component A and B.



② Vacuum out air.



③ Pour potting compound.

Properties

Thermal Conductivity : 2.8 W/m•K

0 0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0 15 20

Hardness : 90 (Shore OO)

0 10 20 30 40 50 60 70 100

Properties	Unit	TG-A09AB / TG-S09AB	Tolerance	Test Method
Thermal Conductivity	W/m•K	2.8	±10%	ASTM D5470 Modified
Color	-	Gray (Mix)	-	-
Dielectric Breakdown Voltage	KV/mm	≥11	-	ASTM D149
Volume Resistivity	Ohm-m	$\geq 10^{12}$	-	ASTMD257
Density	g/cm^3	2.52	±5%	ASTM D792
Operating temperature	° C	-50~+150	-	-
Tensile Strength @3.0mm	kgf/cm^2	230	-	ASTM D412
Elongation	%	55	-	ASTM D412
Viscosity	Pa·s	10~50	-	Brookfield
Weight Loss	%	<1	-	ASTM E595 Modified
Curing Time @25° C	Hrs	6	±10%	-
Curing Time @50° C	Hrs	0.6	±10%	-
Curing Time @80° C	Hrs	0.08	±10%	-
Standard Package	-	Pot	-	-
Hardness	Shore OO	90	±10	-
Mixing Ratio	gram	1:1	-	-

▶ Component A & Component B are mixed material. It is normal to cause precipitation and stratification due to different density. Well mixed component A before use by a flat spatula or other stainless tools to achieve the ideal thermal conductivity.

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